

FAST RECOVERY DIODE

捷多邦, 专业PCB打样工厂, 24小时加急出货

TOSHIBA {DISCRETE/OPTO}

39 DE 9097250 0002242 9

1S2711 1500V 1.5A

MAXIMUM RATINGS

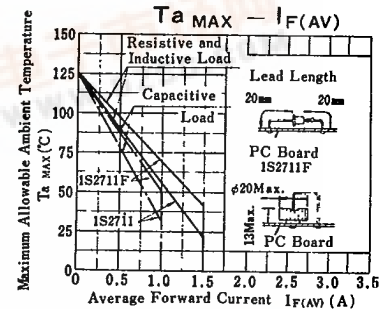
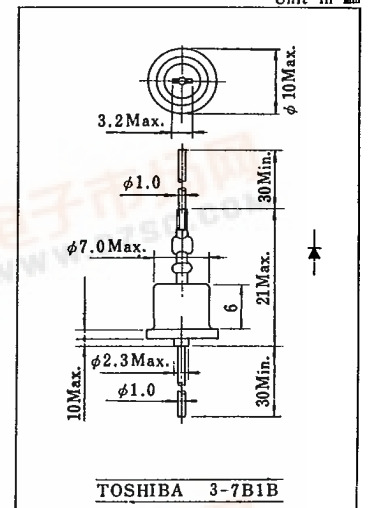
CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	1500	V
Non-Repetitive Peak Reverse Voltage	V_{RSM}	1600	V
Average Forward Current ($T_a=25^\circ\text{C}$)	$I_{F(AV)}$	1.5	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	60(50Hz)	A
Junction Temperature	T_j	-40~125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40~150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	V_{FM}	$I_{FM}=2.0\text{A}, T_j=25^\circ\text{C}$	-	-	1.2	V
Repetitive Peak Reverse Current	I_{RRM} (1)	$V_{RRM}=\text{Rated}, T_j=25^\circ\text{C}$	-	-	10	μA
	I_{RRM} (2)	$V_{RRM}=\text{Rated}, T_j=125^\circ\text{C}$	-	-	600	μA
Reverse Recovery Time	t_{rr}	$I_F=20\text{mA}, I_R=1\text{mA}, T_j=25^\circ\text{C}$	-	-	20	μs
Forward Recovery Voltage	V_{fr}	$I_F=0.1\text{A}, t_r=100\text{ns}, t_p=5\mu\text{s}, T_j=25^\circ\text{C}$	-	-	5	V

Notes : 1. Soldering : 5mm is the minimum to be kept between case and soldering part.

2. Lead Bending : 5mm is the minimum to be kept from the case when bend the lead wire.



3JH61 600V 3A

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	3BH61	100	V
	3DH61	200	
	3GH61	400	
	3JH61	600	
Average Forward Current	$I_{F(AV)}$	1.5 * 1	A
		3.0 * 2	
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	60(50Hz)	A
Junction Temperature	T_j	-40~150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40~150	$^\circ\text{C}$

* 1 No Heat Sink * 2 With Heat Sink

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	V_{FM}	$I_{FM}=3\text{A}, T_j=25^\circ\text{C}$	-	-	1.4	V
Repetitive Peak Reverse Current	I_{RRM} (1)	$V_{RRM}=\text{Rated}, T_j=25^\circ\text{C}$	-	-	20	μA
	I_{RRM} (2)	$V_{RRM}=\text{Rated}, T_j=150^\circ\text{C}$	-	-	3000	
Reverse Recovery Time	t_{rr} (1)	$I_F=20\text{mA}, I_R=1\text{mA}, T_j=25^\circ\text{C}$	-	-	1.5	μs
	t_{rr} (2)	$I_F=20\text{mA}, I_R=20\text{mA}, T_j=25^\circ\text{C}$	-	-	0.5	
Forward Recovery Voltage	V_{fr}	$I_F=0.1\text{A}, t_p=5\mu\text{s}, T_j=25^\circ\text{C}$	-	-	10	V

Notes : 1. Soldering : 5mm is the minimum to be kept between case and soldering part.

2. Lead Bending : 5mm is the minimum to be kept from the case when bend the lead wire.

